

### **Features**

- 3939 UV LED
- Optional Optical Quartz Lens
- ROHS and REACH Compliant
- MSL 4 qualified according to J-STD 020
- ESD 8KV

## **Applications**

- UV Curing
- Medical applications
- Counterfeit Detection
- Purification

## **Description**

The IN-C39(X)TO UV series is a high-power(5W) UV

LED with Good Thermal Dissipation and High

Efficiency. It is a SMD type LED which can be used

in various applications.

.60

.40

.40



1.20

.60

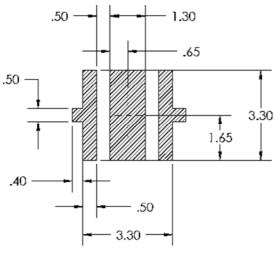
3.20

3.20

1.60

## **Recommended Solder Pattern**

(Suggest Stencil t=0.12 mm)



RECOMMENDED PCB SOLDER PAD

RECOMMENDED PCB SOLDER PAD

RECOMMENDED STENCIL PATTERN (HATCHED AREA IS OPENING)

Figure 1. IN-C39ATO / IN-C39BTO / IN-C39CTO Recommended Solder Pattern

### Note:

- \* All dimensions are in millimeters.
- \* Tolerance is ±0.13mm unless other specified.



# **Package Dimensions**

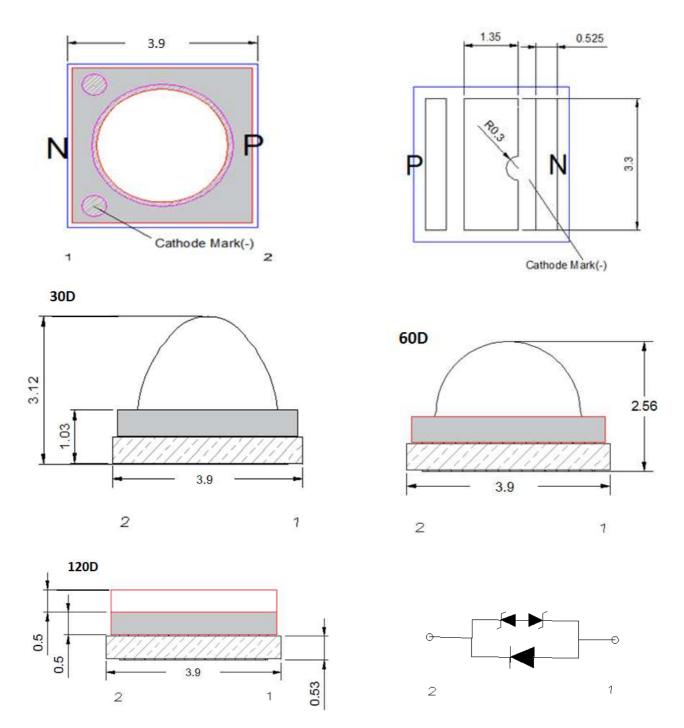


Figure 2. IN-C39ATO / IN-C39BTO / IN-C39CTO Package Dimension

#### Note:

All dimensions are in millimeters.

Tolerance is ±0.13mm unless other specified.

## Absolute Maximum Rating at 25°C

Characteristics	Symbol	Min.	Typical	Max.	Unit
DC Forward Current <sup>1</sup>	I <sub>F</sub>		1000	1200	mA
Pulse Current (@1/10 duty) <sup>2</sup>	I <sub>P</sub>			1800	mA
Forward Voltage	$V_{F}$	3.0		4.4	V
Reverse Voltage	$V_R$			-5	V
Power Dissipation	PD			6.6	W
Leakage Current (5V)	I <sub>R</sub>			10	μΑ
Junction Temperature <sup>3</sup>	Tj		85		$^{\circ}\!\mathbb{C}$
Operating Temperature Range	$T_{opr}$	-40	-	80	$^{\circ}\!\mathbb{C}$
Storage Temperature Range	$T_{stg}$	-40		80	$^{\circ}\!$
Soldering Temperature	T <sub>sol</sub>			260	$^{\circ}\!\mathbb{C}$
Thermal Resistance Junction / Solder Point	R <sub>th</sub>		4.5		°C/W
Viewing Angle <sup>4</sup>	2θ <sub>1/2</sub>		30/60/120		Deg

#### Notes:

- 1. When operating at other than ambient temperature, maximum allowable current depends on derating curves.
- 2. Pulse width = 0.01s & duty factor = 1/10.
- 3. When operating at maximum allowable current, Tj must be below 85 °C.
- 4. Viewing angle tolerance is ± 10°.

## Electrical Characteristics $T_A = 25$ <sup>C</sup> (Note 1)

	V <sub>F</sub> (V)@1000mA			Viewing Angle	I <sub>R</sub> (μA)@V <sub>R</sub> =5V
Product	min	typ	max	<b>2</b> <i>\theta</i> 1/2	max
IN-C39ATO UV Series IN-C39BTO UV Series IN-C39CTO UV Series	3.0		4.4	30/60/120	10

### Notes:

1. Performance guaranteed only under conditions listed in above tables.

### **ESD Precaution**

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

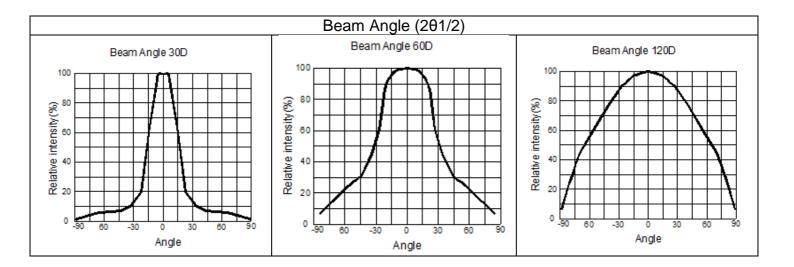
Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).



### **Electronic-Optical Characteristics Relative Spectral Power Distribution** Spectrum Distribution 100 Relative luminous intensity(%) 80 60 385nn 405n 40 20 Wavelength (nm) Forward Current vs. Forward Voltage (Ta=25℃) Relative Radiant Flux vs. Forward Current (Ta=25℃) 1500 160 Relative Power Intensity(%) Forward Current IF (mA) 1300 900 700 140 120 100 80 40 20 900 1100 1300 1500 500 2.0 3.0 4.0 5.0 Forward Current IF (mA) Forward Voltage(VF) -Volts Forward Current vs. Ambient Temperature **Radiant Power vs. Ambient Temperature** 120 Forward Current IF (mA) Relative Power Intensity(%) 100 3939U 39390 60 40 0 0 20 100 100 Ambient Temperature (C) Ambient Temperature (C)

#### Notes:

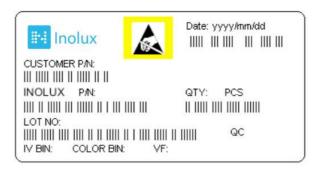
Viewing angle( $2\theta 1/2$ ) ±  $10^{\circ}$ 



# **Ordering Information**

Product	Emission Color	Viewing Angle	Orderable Part Number
		30°	IN-C39ATOU2
	U2:365~370nm	60°	IN-C39BTOU2
		120°	IN-C39CTOU2
		30°	IN-C39ATOU4
IN-C39(X)TO	U4:380~390nm	60°	IN-C39BTOU4
		120°	IN-C39CTOU4
		30°	IN-C39ATOU5
	U5:390~400nm	60°	IN-C39BTOU5
		120°	IN-C39CTOU5

# **Label Specifications**



## **Inolux P/N:**

I	N	-	С	3	9	Х	Т	0		Х	-	Х	Х	X	Х
			Material	Packa	ge	Variation	Orientation	Current	Lens	Color				omiz np-c	
Ino SM			C = Ceramic Type	39B = 3	.9 x 3.9	9 x 3.0, 30 Deg. 9 x 2.5, 60 Deg. x 1.53, 120 Deg.	T = Top Mount	O = 1000mA	(Blank) = Clear	U5 = 390-400nm U4 = 380-390nm U2 = 365-370nm					

## Lot No.:

Z	2	0	1	7	01	24	001
Internal		Voor (2017	Month	Date	Serial		
Tracker		Year (2017, 2018,)				Date	Serial



# **Peak Wavelength Binning**

Peak Wavelength unit: nm@1000mA							
Bin Code		Min	Мах				
U2	R1	365	370				
U4	SA	380	385				
04	SB	385	390				
U5	TA	390	395				
05	ТВ	395	400				

#### Notes:

- 1. Binning current is 1000mA
- 2. Wavelength tolerance ± 2nm

# **Voltage Binning**

	Voltage	unit: V@1000mA	
Peak Wavelength	Bin Code	Min	Max
	V1	3.2	3.4
U2: 365~370nm	V2	3.4	3.6
02. 303 370IIII	V3	3.6	3.8
	V4	3.8	4.0
	V0	3.0	3.2
U4:380~390nm	V1	3.2	3.4
/ U5:390~400nm	V2	3.4	3.6
	V3	3.6	3.8

### Notes:

- 1. Binning current is 1000mA
- 2. Voltage tolerance ± 0.06nm



# Radiant flux (Power) binning

	Radiant flux (Power) unit: mw@1000mA					
Peak Wavelength	Bin Code Min Max					
	H1	1600	1750			
U2: 365~370nm	H2	1750	1900			
	Н3	1900	2050			
	H2	1750	1900			
U4: 380~390nm	H3	1900	2050			
	H4	2050	2200			
	H2	1750	1900			
U5: 390~400nm	H3	1900	2050			
	H4	2050	2200			

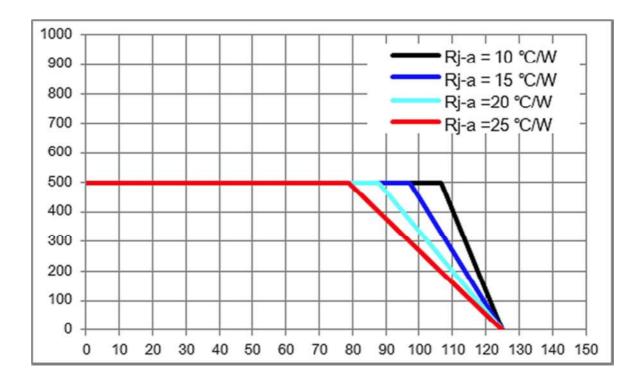
#### Notes:

1. Binning current is 1000mA

2. Power tolerance  $\pm$  10%

## **Thermal Design**

Thermal design of the end product is important. The thermal resistance between the junction and the solder point (ROJ-S) and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (Rja) by the following equation.

Tj = Ta + Rja\*W

Tj = LED junction temperature

Ta = Ambient temperature

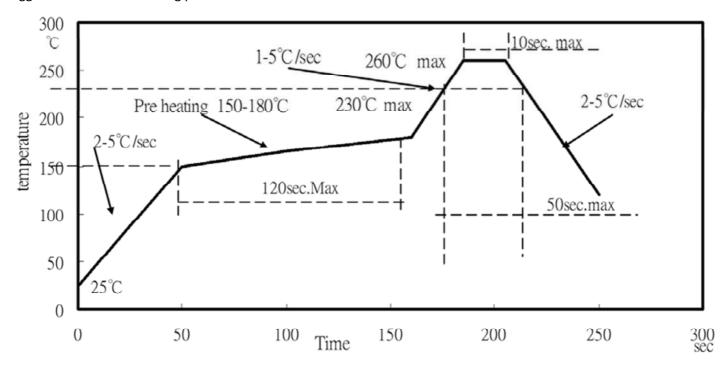
Rja= Thermal resistance between the junction and ambient

 $W = Input power (I_F*V_F)$ 

## **Reflow Soldering**

The LEDs can be soldered using the parameter listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is preferred for the LEDs.

Suggested lead-free soldering profile:

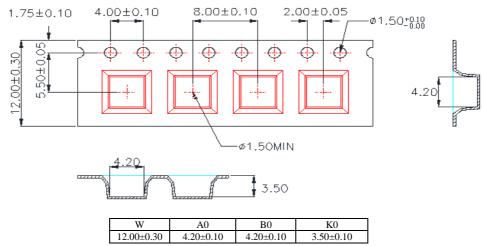


## Notes:

- 1. The recommended reflow temperature is 240°C(±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not stress the silicone resin while it is exposed to high temperature.
- 3. The number of reflow process should not exceed 3 times.

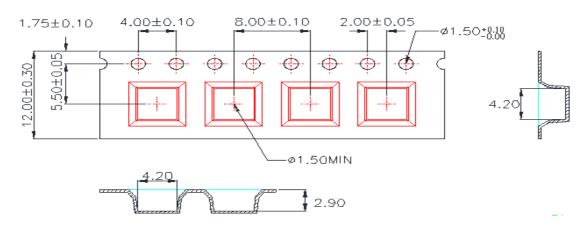
# **Packing**

The carrier tape conforms to EIA-481D.



- 1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.20$ .
- 2. Carrier camber is within 1 mm in 250 mm.3. Material: Black Conductive Polystyrene Alloy.
- 5. Material. Black Conductive Polystyries Arioy.
  4. All dimensions meet EIA-481-D requirements.
  5. Thickness: 0.30±0.05mm
  6. Packing length per 22 " reel: 62.5 Meters (1:3).
  7. Component load per 13" reel: 2500 pcs.

#### 3939 120° / 60°₽

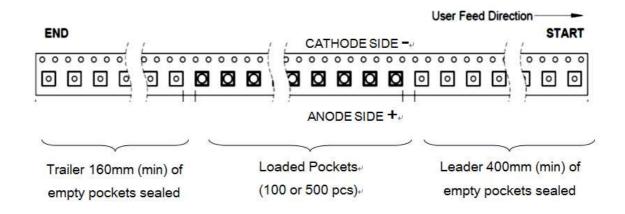


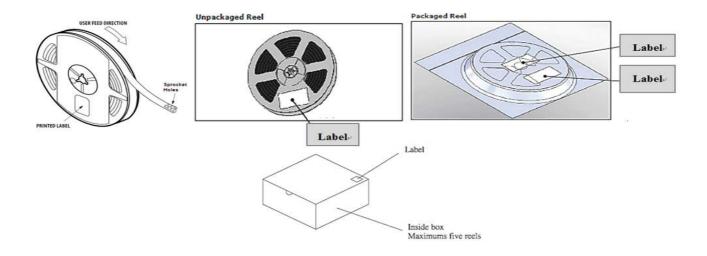
W	A0	В0	K0
12.00±0.30	4.20±0.10	4.20±0.10	3.50±0.10

- 1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.20$ .
- 2. Carrier camber is within 1 mm in 250 mm.3. Material: Black Conductive Polystyrene Alloy.

- 4. All dimensions meet EIA-481-D requirements. 5. Thickness: 0.30±0.05mm 6. Packing length per 22 " reel: 62.5 Meters (1:3).
- 7. Component load per 13" reel: 2500 pcs.







### Notes:

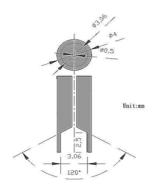
- 1. Each Reel (minimum number of pieces is 100 and maximum is 500 packed in a moisture-proof bag along with 2 packs of desiccant and a humidity indicator card.
- 2. A maximum of 5 moisture-proof bags are packed in an inner box (size: 240mm x 200mm x 105mm  $\pm$  5mm).
- 3. A maximum of 4 inner boxes are put in an outer box (size: 410mm x 255mm x 230mm ±5mm).
- 4. Part No., Lot No., quantity should be indicated on the label of the moisture-proof bag and the cardboard box.

### **Precautions**

- 1. Recommendation for using LEDs
  - 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
  - 1.2 Avoid mechanical stress on LED lens.
  - 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
  - 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging.

### 2. Pick & place nozzle

The pickup tool was recommended and shown as below:



### 3. Lens handling

Please follow the guideline to pick LEDs:

- 3.1 Use tweezers to pick LEDs.
- 3.2 Do not touch the lens by using tweezers.
- 3.3 Do not touch lens with fingers.
- 3.4 Do not apply more than 4N of force (400g) directly onto the lens.

#### 4. Lens cleaning

In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.

- 4.1 Try gently wiping with a dust-free cloth.
- 4.2 If needed, use a dust-free cloth and isopropyl alcohol to gently remove the dirt from the lens surface.
- 4.3 Do not use other solvents as they may react with the LED assembly.
- 4.4 Do not use ultrasonic cleaning which will damage the LEDs.

# Test Items and Results of Reliability

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Thermal Shock	-40°C 30min ↑↓5min 125 °C 30min	100 cycles	0/22	AECQ101
High Temperature Storage	Ta=100°C	1000 hrs	0/22	EIAJ ED-4701 200 201
Humidity Heat Storage	Ta=85℃ RH=85%	1000 hrs	0/22	EIAJ ED-4701 100 103
Low Temperature Storage	Ta=-40°C	1000 hrs	0/22	EIAJ ED-4701 200 202
Life Test	Ta=25℃ lf=500mA	1000 hrs	0/22	Tested with IN standard
High Humidity Heat Life Test	85°C RH=85% If=500mA	1000 hrs	0/22	Tested with IN standard
High Temperature Life Test	Ta=85°C	1000 hrs	0/22	Tested with IN standard
ESD(HBM)	8KV at 1.5kΩ;100pf	3 Times	0/22	MIL-STD-883

Criteria for Judging the Damage								
lk a	Cla a l	Canaditi an	Criteria for Judgment					
ltem	Symbol	Condition	Condition Min	Max				
Forward Voltage	VF	If=500mA	LSL ×0.9	USL ×1.1				
Reverse Current	IR	VR =5V	-	100μΑ				
Luminous Intensity	lv	If=500mA	LSL ×0.7	USL ×1.2				

### Notes:

1. USL: Upper specification level

2. LSL: Lower specification level



**Revision History** 

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	06-28-2018

## **DISCLAIMER**

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